Small Signal MOSFET

60 V, 115 mA, N-Channel SOT-23

Features

- AEC Oualified
- PPAP Capable
- Pb-Free Packages are Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	60	Vdc
Drain-Gate Voltage (R_{GS} = 1.0 M Ω)	V _{DGR}	60	Vdc
Drain Current - Continuous $T_C = 25^{\circ}C$ (Note 1) $T_C = 100^{\circ}C$ (Note 1) - Pulsed (Note 2)	I _D I _D I _{DM}	±115 ±75 ±800	mAdc
Gate-Source Voltage - Continuous - Non-repetitive (t _p ≤ 50 µs)	V _{GS} V _{GSM}	±20 ±40	Vdc Vpk

THERMAL CHARACTERISTICS

Characteristic	Symbol	Мах	Unit
Total Device Dissipation FR-5 Board (Note 3) T _A = 25°C Derate above 25°C	PD	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate,(Note 4) $T_A = 25^{\circ}C$	PD	300	mW mW/°C
Derate above 25°C		2.4	, -
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	– 55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability. 1. The Power Dissipation of the package may result in a lower continuous drain

current.

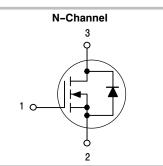
- 2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.
- 3. FR-5 = 1.0 x 0.75 x 0.062 in.
- 4. Alumina = 0.4 x 0.3 x 0.025 in 99.5% alumina.

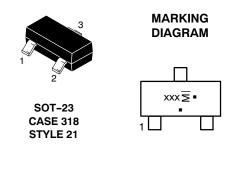


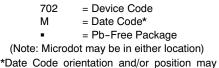
ON Semiconductor®

http://onsemi.com

V _{(BR)DSS}	R _{DS(on)} MAX	I _D MAX
60 V	7.5 Ω @ 10 V, 500 mA	115 mA







vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
2N7002LT1	SOT-23	3000 Tape & Reel
2N7002LT3	00. 10	10,000 Tape & Reel
2N7002LT1G	SOT-23	3000 Tape & Reel
2N7002LT3G	(Pb-free)	10,000 Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

2N7002L

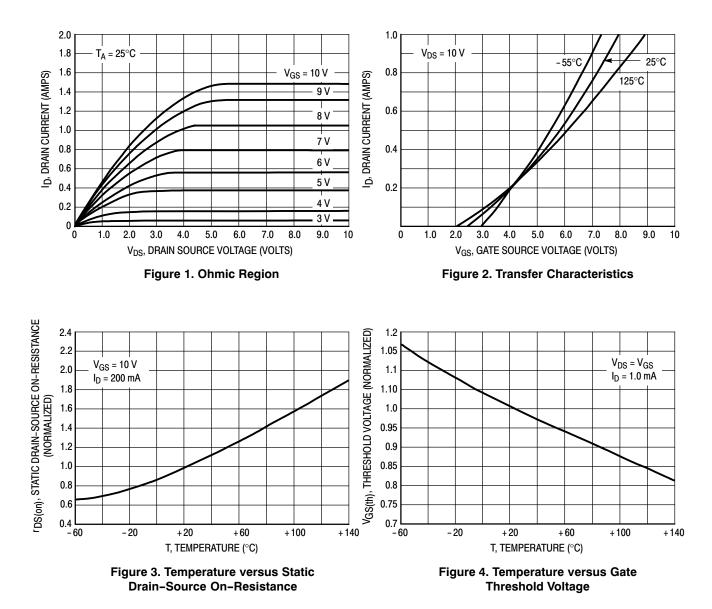
ELECTRICAL CHARACTERISTICS (T_A = 25° C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS			•		•
Drain-Source Breakdown Voltage (V_{GS} = 0, I_D = 10 μ Adc)	V _{(BR)DSS}	60	-	-	Vdc
	I _{DSS}	-		1.0 500	μAdc
Gate-Body Leakage Current, Forward (V _{GS} = 20 Vdc)	I _{GSSF}	-	-	100	nAdc
Gate-Body Leakage Current, Reverse (V _{GS} = -20 Vdc)	I _{GSSR}	-	-	-100	nAdc
ON CHARACTERISTICS (Note 5)				·	
Gate Threshold Voltage $(V_{DS} = V_{GS}, I_D = 250 \ \mu Adc)$	V _{GS(th)}	1.0	-	2.5	Vdc
On-State Drain Current $(V_{DS} \ge 2.0 V_{DS(on)}, V_{GS} = 10 \text{ Vdc})$	I _{D(on)}	500	-	-	mA
Static Drain-Source On-State Voltage (V_{GS} = 10 Vdc, I_D = 500 mAdc) (V_{GS} = 5.0 Vdc, I_D = 50 mAdc)	V _{DS(on)}	-		3.75 0.375	Vdc
	r _{DS(on)}	- - -	- - -	7.5 13.5 7.5	Ohms
$T_{C} = 125^{\circ}C$ Forward Transconductance $(V_{DS} \geq 2.0 \ V_{DS(on)}, \ I_{D} = 200 \ \text{mAdc})$	9fs	80	-	-	mmhos
DYNAMIC CHARACTERISTICS				·	
Input Capacitance $(V_{DS} = 25 \text{ Vdc}, V_{GS} = 0, f = 1.0 \text{ MHz})$	C _{iss}	-	-	50	pF
Output Capacitance $(V_{DS} = 25 \text{ Vdc}, V_{GS} = 0, f = 1.0 \text{ MHz})$	C _{oss}	-	-	25	pF
Reverse Transfer Capacitance $(V_{DS} = 25 \text{ Vdc}, V_{GS} = 0, f = 1.0 \text{ MHz})$	C _{rss}	-	-	5.0	pF
SWITCHING CHARACTERISTICS (Note 5)					
Turn-On Delay Time $(V_{DD} = 25 \text{ Vdc}, I_D \cong 500 \text{ mAdc},$	t _{d(on)}	-	-	20	ns
Turn-Off Delay Time $R_G = 25 \Omega$, $R_L = 50 \Omega$, $V_{gen} = 10 V$)	t _{d(off)}	-	-	40	ns
BODY-DRAIN DIODE RATINGS					
Diode Forward On-Voltage (I _S = 11.5 mAdc, V _{GS} = 0 V)	V _{SD}	-	-	-1.5	Vdc
Source Current Continuous (Body Diode)	I _S	-	-	-115	mAdc
Source Current Pulsed	I _{SM}	-	-	- 800	mAdc

5. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle \leq 2.0%.

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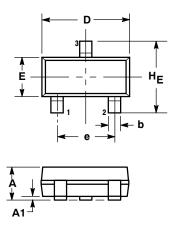
TYPICAL ELECTRICAL CHARACTERISTICS

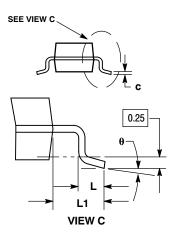


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PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN**





NOTES:

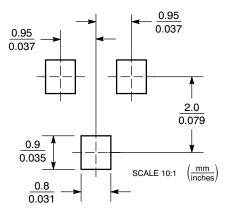
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982 CONTROLLING DIMENSION: INCH.
- З.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08. 4

	М	MILLIMETERS		INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
Е	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 21 PIN 1. GATE SOURCE 2

3

SOLDERING FOOTPRINT



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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